

(19) World Intellectual Property Organization
International Bureau(43) International Publication Date
21 December 2000 (21.12.2000)

PCT

(10) International Publication Number
WO 00/77877 A1(51) International Patent Classification⁶: H01P 1/00, 1/20, H03H 7/38, H01L 25/14, 29/00, 29/82, H01H 51/22

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(21) International Application Number: PCT/US00/16021

(22) International Filing Date: 9 June 2000 (09.06.2000)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/138,865 11 June 1999 (11.06.1999) US
60/173,659 30 December 1999 (30.12.1999) US

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(81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW.

(84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

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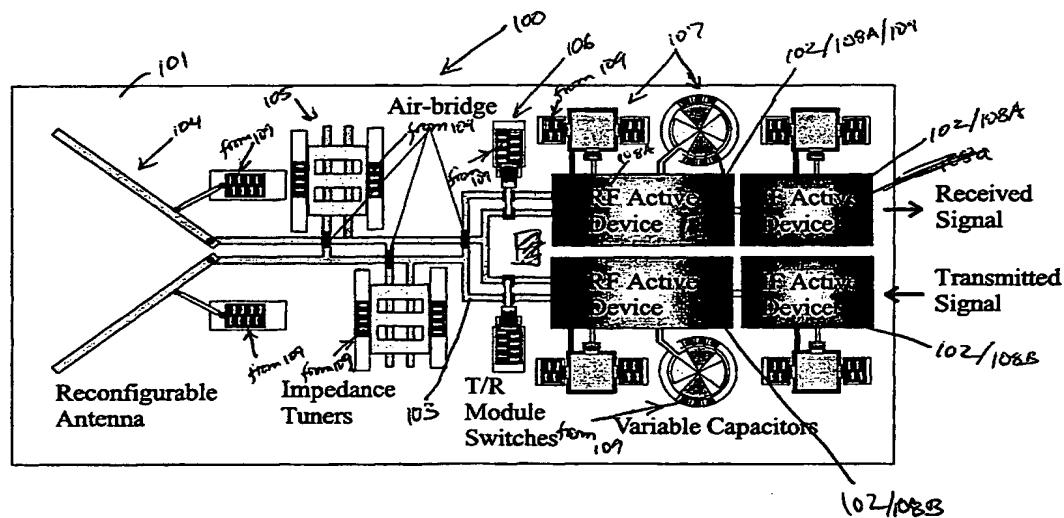
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Published:

- With international search report.
- Before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments.

[Continued on next page]

(54) Title: MEMS TRANSMISSION AND CIRCUIT COMPONENTS



WO 00/77877 A1

(57) Abstract: An Rf device (100) that comprises unique MEMS RF transmission and circuit components (104-106) that are integrated together on a semiconductor chip (101) to form the RF device (100). These MEMS components (104-106) are monolithically formed on the chip (101) and are also reconfigurable on the chip (101).